

# BOYANG CHENG

## PERSONAL INFORMATION

E-mail	bcheng4@nd.edu
Personal e-mail	chengby1998@gmail.com
Phone	+1 (574) 402 8706
ORCID	0000-0003-1003-4960
LinkedIn	<a href="https://www.linkedin.com/in/boyang-cheng/">https://www.linkedin.com/in/boyang-cheng/</a>
Website	<a href="https://cheng-boyang.github.io">https://cheng-boyang.github.io</a>

## EXPERIENCE

2025.5-2025.8	<b>Intern, Logic Pathfinding Lab Research Scientist - DTCO,</b> <i>Samsung Semiconductor, Inc., San Jose, CA, USA</i>
2024.5-2024.8	<b>Intern, Logic Pathfinding Lab Research Scientist - SRAM,</b> <i>Samsung Semiconductor, Inc., San Jose, CA, USA</i>
2020-2022	<b>Research Assistant,</b> <i>Southeast University, Nanjing, Jiangsu, China</i> Advisor: Dr. Weiwei Shan

## EDUCATION

2022-present	<b>Ph.D.</b> <i>University of Notre Dame, Notre Dame, IN, USA</i> Department of Electrical Engineering Advisor: Dr. Ningyuan Cao
2016-2020	<b>B.S.</b> <i>Southeast University, Nanjing, Jiangsu, China</i> School of Internet of Things

## RESEARCH INTERESTS

My current research interests include physical unclonable function (PUF) design, content-addressable memory (CAM) design, compute in memory (CIM), and on-chip entropy source design.

## SELECTED PUBLICATIONS

### Conferences

2025	L. Pei, Y. Zhou, X. Wang, X. Zhao, W. Huang, <b>B. Cheng</b> , H. Mulaosmanovic, S. Duenkel, D. Kleimaier, S. Beyer, K. Ni, M. Hou, M. Niemier, N. Cao, "Towards Uncertainty-aware Robotic Perception via Mixed-signal BNN Engine Leveraging Probabilistic Quantum Tunneling," in <b>DAC '25</b>
2025	J. Liu, Z. Enciso, <b>B. Cheng</b> , L. Pei, S. Davis, Y. Qin, Z. Jia, X. S. Hu, Y. Shi, and N. Cao, "15.3 A 65nm Uncertainty-quantifiable Ventricular Arrhythmia Detection Engine with $1.75 \mu\text{J}$ per Inference," in <b>ISSCC '25</b>
2024	L. Pei, Y. Qin, Z. Enciso, <b>B. Cheng</b> , J. Liu, S. Davis, Z. Jia, M. Niemier, Y. Shi, X. S. Hu, and N. Cao, "Towards Uncertainty-Quantifiable Biomedical Intelligence: Mixed-signal Compute-in-Entropy for Bayesian Neural Networks," in <b>ICCAD '24 (Best Paper Award Nominee)</b>
2024	J. Liu, <b>B. Cheng</b> , Z. Enciso, S. Davis, and N. Cao, "CIPUF: Towards On-chip Learnable Anomaly Detection with Compute-In-PUF Architecture," in <b>ISLPED '24</b>

- 2024 **B. Cheng**, J. Liu, S. Davis, Z. Enciso, Y. Zhang, and N. Cao, "VAE-HDC: Efficient and Secure Hyper-dimensional Encoder Leveraging Variation Analog Entropy," in **DAC '24**
- 2024 **B. Cheng**, J. Liu, S. Davis, Z. Enciso, L. Pei, M. Chang, and N. Cao, "A 65 nm Neuromorphic Bio-Signal Encoder with Compute-in-Entropy Architecture 7.13 nJ Privacy-Preserving Encoding and 2.38 Mb/mm<sup>2</sup> Item Memory Density," in **VLSI '24**
- 2023 J. Liu, **B. Cheng**, P. Zeng, S. Davis, M. Chang and N. Cao, "Privacy-by-Sensing with Time-domain Differentially-Private Compressed Sensing," in **DATE '23**
- 2022 N. Cao, J. Liu, **B. Cheng**, and M. Chang, "Stochastic Mixed-Signal Circuit Design for In-Sensor Privacy," in **ICCAD '22**

### *Journals*

- 2025 J. Liu, **B. Cheng**, X. Zhao, et al., "A Physically-Unclonable Bio-Signal Encoder for Privacy-preserving IoMT Applications," in **IEEE Internet of Things Journal (IoTJ)**
- 2024 S. Davis, J. Liu, **B. Cheng**, M. Chang and N. Cao, "In-Situ Privacy via Mixed-Signal Perturbation and Hardware-Secure Data Reversibility," in **TCAS-I**
- 2023 Y. Du, Z. Chen, **B. Cheng**, and W. Shan, "Design and analysis of leading one/zero detector based approximate multipliers," in **Microelectronics Journal**
- 2023 Z. Chen, Y. Du, **B. Cheng**, and W. Shan, "Design of high-efficiency complex multiplier for fault-tolerant computation," in **Integration**
- 2022 N. Cao, B. Chatterjee, J. Liu, **B. Cheng**, et al., "A 65 nm Wireless Image SoC Supporting On-Chip DNN Optimization and Real-Time Computation-Communication Trade-Off via Actor-Critical Neuro Controller" in **JSSC**
- 2021 Z. Cai, **B. Cheng**, Y. Du, X. Shang and W. Shan, "A Time-Domain Binary CNN Engine With Error-Detection-Based Resilience in 28nm CMOS," in **TCAS-II**

### **PATENTS**

- 2021 **Ultra-low Power Keyword Spotting Neural Network Circuit**, U.S. Patent

### **PEER REVIEWS**

- IEEE Transactions on Very Large Scale Integration (VLSI) Systems (**TVLSI**)  
 IEEE Sensors Letters  
 IEEE Transactions on Industrial Electronics (**TIE**)

### **SKILLS**

- Skills:** Analog/Mixed-signal IC, Digital IC, RISC-V, Floor Planning, Customize Layout, Timing Convergence
- Software and Tools:** Virtuoso (SKILL), Innovus, Design Compiler, Python, System C, Catapult, C++, Verilog, Calibre (SVRF)